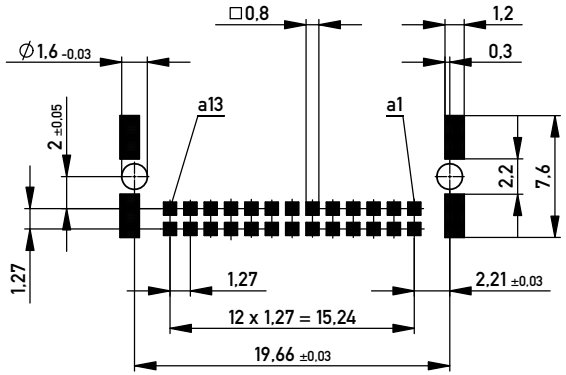
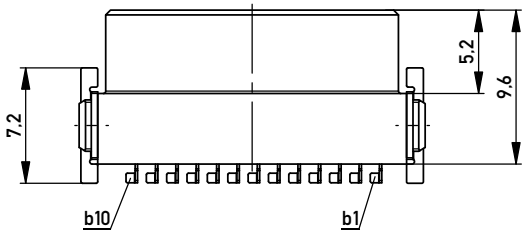
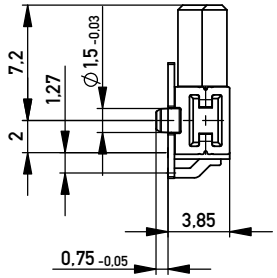
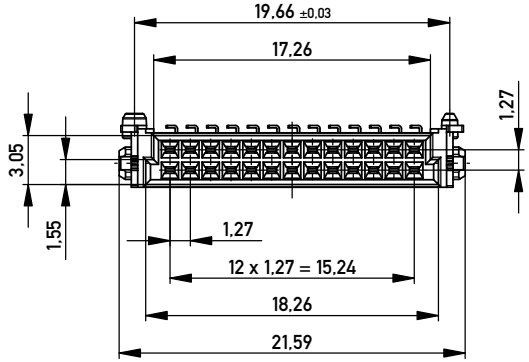
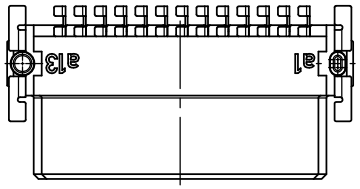
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT











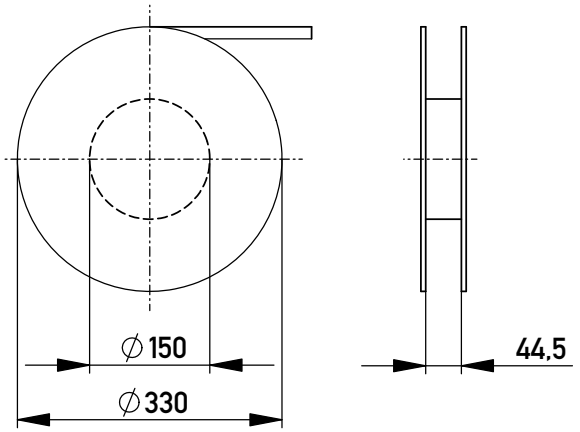
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

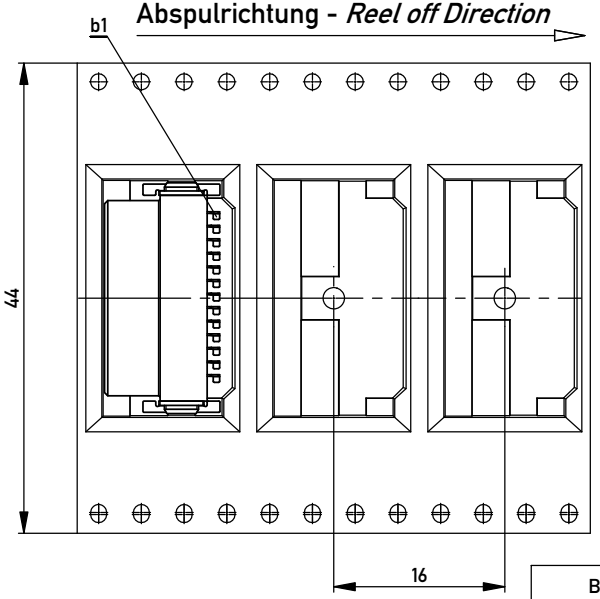
Anschlussbereich verzinnt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt in Gurtverpackung - *Tape on Reel Packaging*
Verpackungseinheit: 560 Stück - *Packaging unit: 560 pcs*



Abspulrichtung - *Reel off Direction*



BA7-03 - Standard Bauhöhe
type7-03 - standard assembly height

Information:	Tolerances	All Dimensions in mm	Scale 3:1

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Subject to modification without prior notice.
Drawing will not be updated.

Designation
Federl. SMC-Q 26-SMD-BA7-03
Female SMC-Q 26-SMD-type7-03

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154741 | I | A3

Index	Date	Class
e	04.04.2011	SMCQ